

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









# **Film Capacitors**

EMI Suppression Capacitors (MKP)

Series/Type: B32922H/J ... B32926H/J

Date: July 2016

© EPCOS AG 2016. Reproduction, publication and dissemination of this publication, enclosures hereto and the information contained therein without EPCOS' prior express consent is prohibited.

EPCOS AG is a TDK Group Company.

#### X2 / 305 V AC

#### **Typical applications**

- X2 class for interference suppression
- "Across the line" applications
- Severe ambient conditions
- For connections in series with the mains
- Capacitive power supply
- Energy meters

#### Climatic

- Max. operating temperature: 110 °C
- Climatic category (IEC 60068-1): 40/110/56

#### Construction

- Dielectric: metallised polypropylene (MKP)
- Wound film technology
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

#### **Features**

- Self-healing properties
- High stability of capacitance value

#### **Terminals**

- Parallel wire leads
- Lead-free tinned
- Standard lead lengths: 6-1 mm
- Special lead lengths available on request

#### Marking

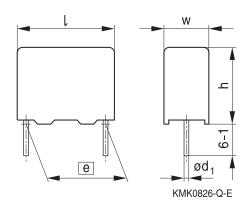
Manufacturer's logo, lot number, date code, rated capacitance (coded), cap. tolerance (code letter), rated AC voltage, series number, sub-class (X2), dielectric code (MKP), climatic category, passive flammability category, approvals

#### **Delivery mode**

Bulk (untaped)
Taped (Ammo pack or reel)
For taping details, refer to chapter
"Taping and packing"

## **Dimensional drawings**

## **Drawing A1**



#### Dimensions in mm

Number	Lead	Lead	Туре
of	spacing	diameter	· ·
wires	<i>e</i> ±0.4	d₁ ±0.05	
2-pin	15.0	0.8	B32922 H/J
2-pin	22.5	0.8	B32923 H/J
2-pin	27.5	0.8	B32924 H/J
2-pin	37.5	1.0	B32926 H/J



X2 / 305 V AC



# **Marking Examples**



# **Approvals**

Approval marks	Standards	Certificate
<b>4</b> 15	EN 60384-14, IEC 60384-14, Ed. 3	ENEC-00812 (approved by UL)
c <b>FL</b> us	UL 60384-14, CSA E60384-14	E97863 (approved by UL)



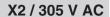


# X2/305 V AC

# Overview of available types

Lead spacing	15 mm	22.5 mm	27.5 mm	37.5 mm
Туре	B32922 H/J	B32923 H/J	B32924 H/J	B32926 H/J
C <sub>R</sub> (μF)				
0.10				
0.15				
0.2				
0.22				
0.33				
0.410				
0.47				
0.56				
0.68				
0.82				
1.0				
1.5				
2.2				
3.3				
4.7				
6.8				
8.2				
10				
15				







# Ordering codes and packing units

Lead	C <sub>R</sub>	Max. dimensions	Ordering code	Straight	Straight	Straight
spacing		$w \times h \times I$	(composition see	terminals,	terminals,	terminals,
mm	μF	mm	below)	Ammo	Reel	Untaped
				pack		
				pcs./MOQ	pcs./MOQ	pcs./MOQ
15	0.10	$6.0 \times 11.0 \times 18.0$	B32922H3104+***	3840	4400	4000
	0.15	$7.0 \times 12.5 \times 18.0$	B32922H3154+***	3320	3600	4000
	0.20	$8.0 \times 14.0 \times 18.0$	B32922H3204+***	2920	3000	2000
	0.22	$8.0 \times 14.0 \times 18.0$	B32922H3224M***	2920	3000	2000
	0.22	$8.5 \times 14.5 \times 18.0$	B32922J3224+***	2720	2800	2000
	0.33	$9.0 \times 17.5 \times 18.0$	B32922H3334+***	2560	2800	2000
	0.47	$11.0\times18.5\times18.0$	B32922H3474+***	_	2200	1200
22.5	0.22	$7.0\times16.0\times26.5$	B32923H3224+***	2320	2400	2520
	0.33	$8.5\times16.5\times26.5$	B32923J3334+***	1920	2000	2040
	0.41	$8.5\times16.5\times26.5$	B32923H3414M***	1920	2000	2040
	0.47	$10.5\times16.5\times26.5$	B32923H3474+***	1560	1600	2160
	0.56	$10.5\times18.5\times26.5$	B32923H3564+***	1560	1600	2160
	0.68	$10.5\times18.5\times26.5$	B32923H3684M***	1560	1600	2160
	0.68	$11.0\times20.5\times26.5$	B32923J3684+***	_	_	2040
	0.82	$11.0\times20.5\times26.5$	B32923H3824+***	_	_	2040
	1.0	$12.0 \times 22.0 \times 26.5$	B32923H3105+***	_	_	1800
	1.5	$14.5 \times 29.5 \times 26.5$	B32923H3155+***	_	_	1040
	2.2	$14.5 \times 29.5 \times 26.5$	B32923H3225M***	_	_	1040

## MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further intermediate capacitance values on request.

#### Composition of ordering code

+ = Capacitance tolerance code:

 $M = \pm 20\%$ 

 $K = \pm 10\%$ 

\*\*\* = Packaging code:

289 = Straight terminals, Ammo pack for lead spacing 15 mm and 22.5 mm

189 = Straight terminals, Reel

255 = Crimped down from lead spacing 15 mm to 7.5 mm, Ammo pack

155 = Crimped down from lead spacing 15 mm to 7.5 mm, Reel

003 = Straight terminals, untaped (lead length  $3.2 \pm 0.3 \text{ mm}$ )

000 = Straight terminals, untaped (lead length 6 - 1 mm)





## X2/305 V AC

## Ordering codes and packing units

Lead	C <sub>R</sub>	Max. dimensions	Ordering code	Straight	Straight	Straight
spacing		$w \times h \times I$	(composition see	terminals,	terminals,	terminals,
mm	μF	mm	below)	Ammo	Reel	Untaped
				pack		
				pcs./MOQ	pcs./MOQ	pcs./MOQ
27.5	0.68	$11.0 \times 19.0 \times 31.5$	B32924H3684+***	_	1400	1280
	1.0	$11.0 \times 21.0 \times 31.5$	B32924H3105+***	_	1400	1280
	1.5	$13.5 \times 23.0 \times 31.5$	B32924H3155M***	_	1000	1040
	1.5	$14.0 \times 24.5 \times 31.5$	B32924J3155+***	_	_	1040
	2.2	$16.0 \times 32.0 \times 31.5$	B32924J3225+***	_	_	880
	2.2	$18.0 \times 27.5 \times 31.5$	B32924H3225+***	_	_	800
	3.3	$18.0 \times 33.0 \times 31.5$	B32924J3335+***	_	_	800
	3.3	$19.0 \times 30.0 \times 31.5$	B32924H3335M***	_	_	720
	4.7	$22.0 \times 36.5 \times 31.5$	B32924H3475+***	_	_	640
37.5	2.2	$14.0 \times 25.0 \times 42.0$	B32926H3225+***	_	_	1380
	3.3	$16.0 \times 28.5 \times 42.0$	B32926H3335+***	-	_	800
	4.7	$18.0 \times 32.5 \times 42.0$	B32926H3475+***	_	_	720
	6.8	$20.0 \times 39.5 \times 42.0$	B32926H3685+***	_	_	640
	8.2	$28.0 \times 37.0 \times 42.0$	B32926J3825+***	_	_	440
	10.0	$28.0 \times 37.0 \times 42.0$	B32926H3106M***	_	_	440
	10.0	$28.0 \times 42.5 \times 42.0$	B32926J3106+***	_	_	440
	15.0	$33.0 \times 48.0 \times 42.0$	B32926H3156+***	_	_	180

## MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further intermediate capacitance values on request.

#### Composition of ordering code

+ = Capacitance tolerance code:

 $M = \pm 20\%$ 

 $K = \pm 10\%$ 

\*\*\* = Packaging code:

289 = Straight terminals, Ammo pack for lead spacing 15 mm and 22.5 mm

189 = Straight terminals, Reel

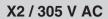
255 = Crimped down from lead spacing 15 mm to 7.5 mm, Ammo pack

155 = Crimped down from lead spacing 15 mm to 7.5 mm, Reel

003 = Straight terminals, untaped (lead length 3.2 ±0.3 mm)

000 = Straight terminals, untaped (lead length 6 - 1 mm)







# **Technical data and specifications**

Reference standard: IEC / UL 60384-14. All data given at T = 20  $^{\circ}$ C unless otherwise specified.

Rated AC voltage (IEC 60384-14)	305 V AC (50/60 Hz)					
$\begin{tabular}{ll} \hline Maximum continuous DC voltage $V_{DC}$ \\ \hline \end{tabular}$	630 V DC					
DC voltage test	Between term	Between terminals: 1312 V DC / 2 s				
The repetition of this DC voltage test r	nay damage th	e capacito	or. Special	care n	nust	be taken
incase of use several capacitors in a p	parallel configui	ration.				
Max. operating temperature T <sub>op,max</sub>	+110 °C					
Dissipation factor tan $\delta$ (in 10 <sup>-3</sup> )		C <sub>R</sub> ≤0.1 μ	F 0.1μF<0	C <sub>R</sub> ≤2.	2 μF	$C_R > 2.2 \mu F$
at 20 °C (upper limit values)	at 1 kHz	1.0	1.0			2.0
	100 kHz	5.0	_			_
Insulation resistance $R_{\text{ins}}$ (in $G\Omega)$	$C_R \le 0.33 \ \mu F$			$C_R >$	0.33	μF
or time constant $\tau = C_R \cdot R_{ins}$ (in s)	100 GΩ			30 00	00 s	
at 20 °C, rel. humidity ≤ 65%						
(minimum as-delivered values)						
Operating AC voltage $V_{\text{op}}$ at high	T <sub>op</sub> ≤ 110 °C	,	$V_{op} = V_{AC}$		(cor	ntinuously)
temperature	T <sub>op</sub> ≤ 110 °C	,	$V_{op} = 1.25$	· V <sub>AC</sub>	(100	00 h)
Passive flammability category	В					
Damp heat test	Test 1:	Tempera	ture:		85 °	C±2 °C
		Relative I	humidity (F	RH):	85%	%±2%
		Test duration:			100	0 h
		Voltage value:			240	V AC, 50 Hz
	Test 2:	Tempera	ture:		60 °	C±2 °C
		Relative humidity (RH):			95%	%±2%
		Test duration:			100	0 h
		Voltage v	alue:		240	V AC, 50 Hz
Limit values after damp heat test	Capacitance of	change (∆	C/C): ≤ 10°	%		
	Dissipation fa	ctor chanc	ae (∆tan δ):	≤5.	10-3	(at 1 kHz)
	for lead spaci	-				( )
	Dissipation fa	_			10-2	(at 1 kHz)
	for lead spaci	ng 27.5 m	m and 37.5	5 mm		
	$\Delta$ tan $\delta$ /tan $\delta$ ≤	2000% (a	t 10 kHz)			
	Insulation resi	stance R <sub>ir</sub>	ns: ≥ 200 M	Ω		
Reference standard	AEC-Q200					





## X2/305 V AC

## Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in  $V/\mu s$ .

" $k_0$ " represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in  $V^2/\mu s$ .

#### Note:

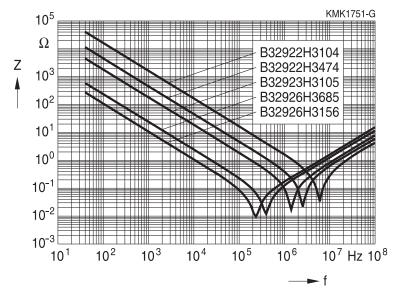
The values of dV/dt and  $k_0$  provided below must not be exceeded in order to avoid damaging the capacitor.

# dV/dt and ko values

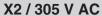
Lead spacing	15 mm	22.5 mm	27.5 mm	37.5 mm
dV/dt in V/μs	340	170	120	80
k <sub>0</sub> in V²/μs	292400	146200	103200	68800

# Impedance Z versus frequency f

(typical values)



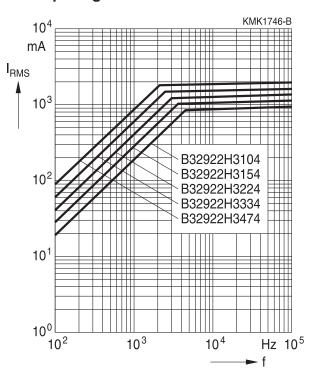




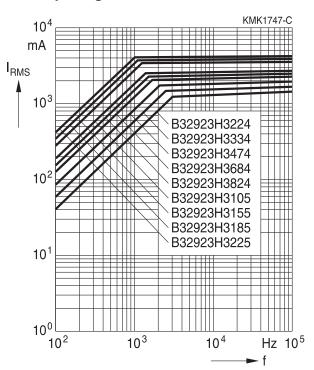


Permissible AC current  $I_{RMS}$  versus frequency f (for sinusoidal waveform, TA  $\leq$  90  $^{\circ}$ C and  $\triangle$ ESR < 100% from receipt condition)

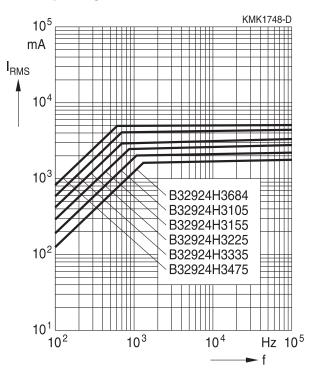
## Lead spacing 15 mm



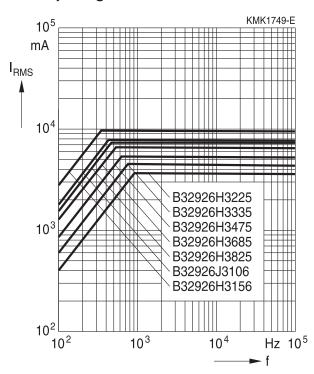
## Lead Spacing 22.5 mm



## Lead spacing 27.5 mm



## Lead spacing 37.5 mm





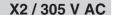


# X2/305 V AC

# **Testing and Standards**

Test	Reference	Conditions of test		Performance requirements
Electrical Parameters	IEC 60384-14	Voltage Proof: Between terminals: $4.3 \times V_R$ (DC), 2s Terminals and enclosure: $2 V_R + 1500 V$ AC Insulation resistance, R <sub>INS</sub> Capacitance, C Dissipation factor, tan $\delta$		Within specified limits
Robustness of termina- tions	IEC 60068-2-21		t Ua1) Tensile force 10 N 20 N	Capacitance and tan δ within specified limits
Resistance to soldering heat	IEC 60068-2-20, test Tb, method 1A	Solder bath tempera $260 \pm 5$ °C, immersion 10 seconds		$\Delta C/C_0 \le 5\%$ tan $\delta$ within specified limits
Rapid change of temperature	IEC 60384-14	$T_A$ = lower category temperature $T_B$ = upper category temperature Five cycles, duration t = 30 min.		No visible damage $ \Delta C/C_0  \leq 5\%$ tan $\delta$ within specified limits
Vibration	IEC 60384-14	Test F <sub>c</sub> : vibration sinusoidal Displacement: 0.75 mm Accleration: 98 m/s <sup>2</sup> Frequency: 10 Hz 500 Hz Test duration: 3 orthogonal axes, 2 hours each axe		No visible damage
Bump	IEC 60384-14	400 m/s² mounted on PCB		No visible damage $I\Delta C/C_0I \leq 5\%$ tan $\delta$ within specified limits
Damp Heat Steady State	IEC 60384-14	Test Ca 40 °C / 93% RH / 56 days		No visible damage $\begin{split} &I\Delta C/C_0I \leq 5\% \\ &I\Delta\ tan\ \delta I \leq 0.008\ for\ C \leq 1\ \mu F \\ &I\Delta\ tan\ \delta I < 0.005\ for\ C > 1\ \mu F \\ &Voltage\ proof \\ &R_{INS} \geq 50\%\ of\ initial\ limit \end{split}$
Impulse test Endurance	IEC 60384-14	3 impulses $T_{\rm B}$ / 1.25 $V_{\rm R}$ / 1000 hours, 1000 $V_{\rm rms}$ for 0.1 s every hour		No visible damage $\begin{split} &I\Delta C/C_0I \leq 10\% \\ &I\Delta \ tan \ \delta I \leq 0.008 \ for \ C \leq 1 \ \mu F \\ &I\Delta \ tan \ \delta I < 0.005 \ for \ C > 1 \ \mu F \\ &Voltage \ proof \\ &R_{\text{INS}} \geq 50\% \ of \ initial \ limit \end{split}$







Test	Reference	Conditions of test	Performance requirements
Passive flammability	IEC 60384-14	Flame applied for a period of time depending on capacitor volume	В
Active flammability	IEC 60384-14	20 discharges at 2.5 kV + V <sub>R</sub>	The cheesecloth shall not burn with a flame

## **Mounting guidelines**

#### 1 Soldering

## 1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

#### 1.2 Resistance to soldering heat

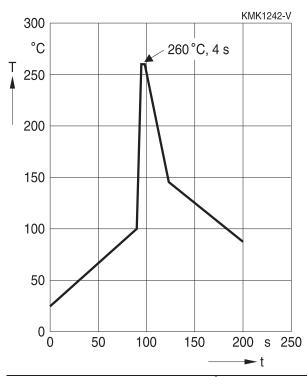
Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A. Conditions:

Series	S	Solder bath temperature	Soldering time
MKT	boxed (except $2.5 \times 6.5 \times 7.2$ mm)	260 ±5 °C	10 ±1 s
	coated		
	uncoated (lead spacing > 10 mm)		
MFP			
MKP	(lead spacing > 7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5 ±1 s
MKP	(lead spacing ≤ 7.5 mm)		< 4 s
MKT	uncoated (lead spacing ≤ 10 mm)		recommended soldering
	insulated (B32559)		profile for MKT uncoated
			(lead spacing ≤ 10 mm) and
			insulated (B32559)





# X2/305 V AC



Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 $\pm$ 0.5) mm thick, between capacitor
	body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
A C /C	2% for MKT/MKP/MFP
$\Delta C/C_0$	5% for EMI suppression capacitors
$tan \delta$	As specified in sectional specification



X2 / 305 V AC



#### 1.3 General notes on soldering

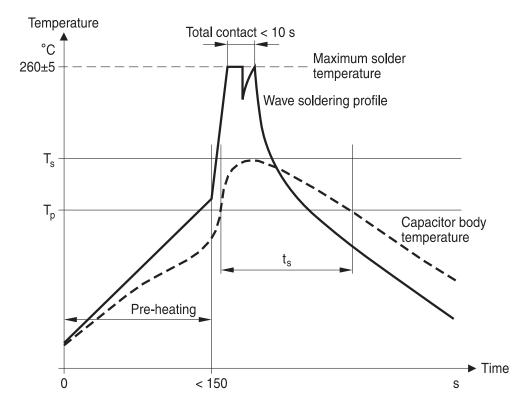
Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature  $T_{\text{max}}$ . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics: diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

#### **EPCOS** recommendations

As a reference, the recommended wave soldering profile for our film capacitors is as follows:



T<sub>s</sub>: Capacitor body maximum temperature at wave soldering

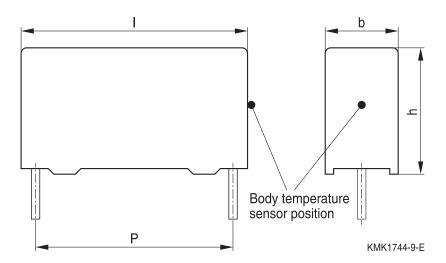
T<sub>p</sub>: Capacitor body maximum temperature at pre-heating

KMK1745-A-E





#### X2 / 305 V AC



Body temperature should follow the description below:

MKP capacitor

During pre-heating: T<sub>p</sub> ≤ 110 °C

During soldering:  $T_s \le 120 \, ^{\circ}\text{C}$ ,  $t_s \le 45 \, \text{s}$ 

MKT capacitor

During pre-heating: T<sub>p</sub> ≤ 125 °C

During soldering:  $T_s \le 160 \, ^{\circ}\text{C}$ ,  $t_s \le 45 \, \text{s}$ 

When SMD components are used together with leaded ones, the film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.

Leaded film capacitors are not suitable for reflow soldering.

For uncoated MKT capacitors with lead spacings ≤ 10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering

For manual soldering or selective soldering, body temperature  $T_s \le 120~^{\circ}\text{C}$  is also required to qualify soldering condition. One recommended condition for manual soldering is that soldering iron tip temperature below 360  $^{\circ}\text{C}$ , and soldering contact time not more than 3 seconds.

Please refer to EPCOS Film Capacitor Data Book in case more details are needed.



X2 / 305 V AC



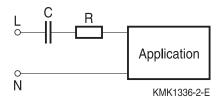
#### Application note for the different possible X1 / X2 positions

# In series with the powerline (i.e. capacitive power supply)

Typical Applications:

- Power meters
- ECUs for white goods and household appliances
- Different sensor applications
- Severe ambient conditions

#### **Basic circuit**



#### Required features

- High capacitance stability over the lifetime
- Narrow tolerances for a controlled current supply

#### **Recommended EPCOS product series**

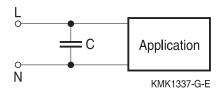
- B3293\* (305 V AC) heavy duty with EN approval for X2 (UL Q1/2010)
- B3265\* MKP series standard MKP capacitor without safety approvals
- B3267\*L MKP series standard MKP capacitor without safety approvals
- B3292\*H/J (305 V AC), severe ambient condition, approved as X2

# In parallel with the powerline

Typical Applications:

Standard X2 are used parallel over the mains for reducing electromagnetic interferences coming from the grid. For such purposes they must meet the applicable EMC directives and standards.

#### **Basic circuit**



#### **Required features**

- Standard safety approvals (ENEC, UL, CSA, CQC)
- High pulse load capability
- Withstand surge voltages

#### **Recommended EPCOS product series**

- B3292\*C/D (305 V AC) standard series, approved as X2
- B3291\* (330 V AC), approved as X1
- B3291\* (530 V AC), approved as X1
- B3292\*H/J (305 V AC), severe ambient condition, approved as X2





#### X2 / 305 V AC

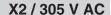
#### **Cautions and warnings**

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"







Topic	Safety information	Reference chapter
		"General technical
		information"
Topic	Safety information	Reference chapter
		"Mounting guidelines"
Soldering	Do not exceed the specified time or temperature	1 "Soldering"
	limits during soldering.	
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of	When embedding finished circuit assemblies in	3 "Embedding of
capacitors in	plastic resins, chemical and thermal influences	capacitors in finished
finished assemblies	must be taken into account.	assemblies"
	Caution: Consult us first, if you also wish to	
	embed other uncoated component types!	

#### **Design of EMI Capacitors**

EPCOS EMI capacitors use polypropylene (PP) film metalized with a thin layer of Zinc (Zn). The following key points have made this design suitable to IEC/UL testing, holding a minimum size.

- Overvoltage AC capability with very high temperature Endurance test of IEC60384-14 ( $3^{rd}$  edition, 2005-07) / UL60384-14 (1st edition, 2009-04) must be performed at  $1.25 \times V_R$  at maximum temperature, during 1000 hours, with a capacitance drift less than 10%.
- Higher breakdown voltage withstanding if compared to other film metallizations, like Aluminum. IEC60384-14 (3<sup>rd</sup> edition, 2005-07) / UL60384-14 (1st edition, 2009-04) establishes high voltage tests performed at  $4.3 \times V_R$  −1 minute, impulse testing at 2500 V for C= 1 μF and active flammability tests.
- Damp heat steady state: 40 °C/ 93% RH / 56 days. (without voltage or current load)

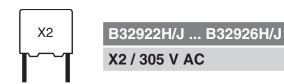
## Effect of humidity on capacitance stability

Long contact of a film capacitor with humidity can produce irreversible effects. Direct contact with liquid water or excess exposure to high ambient humidity or dew will eventually remove the film metallization and thus destroy the capacitor. Plastic boxed capacitors must be properly tested in the final application at the worst expected conditions of temperature and humidity in order to check if any parameter drift may provoke a circuit malfunction.

In case of penetration of humidity through the film, the layer of Zinc can be degraded, specially under AC operation (change of polarity), accelerated by the temperature, provoking an increment of the serial resistance of the electrode and eventually a reduction of the capacitance value. For DC operation, the parameter drift is much less.

Plastic boxes and resins can not protect 100% against humidity. Metal enclosures, resin potting or coatings or similar measures by customers in their applications will offer additional protection against humidity penetration.





## Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <a href="https://www.epcos.com/orderingcodes">www.epcos.com/orderingcodes</a>.







# Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
$\alpha_{\text{C}}$	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
Α	Capacitor surface area	Kondensatoroberfläche
$\beta_{C}$	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
$C_R$	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
ΔC/C	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔΤ	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
∆tan δ	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
$\Delta V$	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f <sub>1</sub>	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
$f_2$	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
f <sub>r</sub>	Resonant frequency	Resonanzfrequenz
$F_{D}$	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
$F_T$	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I <sub>C</sub>	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)





# X2/305 V AC

Symbol	English	German
I <sub>RMS</sub>	(Sinusoidal) alternating current,	(Sinusförmiger) Wechselstrom
	root-mean-square value	
i <sub>z</sub>	Capacitance drift	Inkonstanz der Kapazität
$k_0$	Pulse characteristic	Impulskennwert
Ls	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
$\lambda_0$	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
$\lambda_{test}$	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
$P_{diss}$	Dissipated power	Abgegebene Verlustleistung
$P_{gen}$	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
$R_{i}$	Internal resistance	Innenwiderstand
R <sub>ins</sub>	Insulation resistance	Isolationswiderstand
$R_P$	Parallel resistance	Parallelwiderstand
$R_s$	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan $\delta$	Dissipation factor	Verlustfaktor
$\tan \delta_{\scriptscriptstyle D}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan $\delta_{P}$	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan $\delta_{\text{S}}$	Series component of dissipation factor	Serienanteil des Verlustfaktors
T <sub>A</sub>	Temperature of the air surrounding the component	Temperatur der Luft, die das Bauteil umgibt
$T_{max}$	Upper category temperature	Obere Kategorietemperatur
T <sub>min</sub>	Lower category temperature	Untere Kategorietemperatur
t <sub>OL</sub>	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
- <del>-</del>	and voltage	-spannung
T <sub>op</sub>	Operating temperature	Beriebstemperatur
T <sub>R</sub>	Rated temperature	Nenntemperatur
T <sub>ref</sub>	Reference temperature	Referenztemperatur
t <sub>SL</sub>	Reference service life	Referenz-Lebensdauer







Symbol	English	German
$V_{AC}$	AC voltage	Wechselspannung
$V_{C}$	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
$V_{CD}$	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
$V_{ch}$	Charging voltage	Ladespannung
$V_{DC}$	DC voltage	Gleichspannung
$V_{FB}$	Fly-back capacitor voltage	Spannung (Flyback)
$V_{i}$	Input voltage	Eingangsspannung
$V_{o}$	Output voltage	Ausgangssspannung
$V_{op}$	Operating voltage	Betriebsspannung
$V_p$	Peak pulse voltage	Impuls-Spitzenspannung
$V_{pp}$	Peak-to-peak voltage Impedance	Spannungshub
$V_R$	Rated voltage	Nennspannung
Ŷ <sub>R</sub>	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
$V_{RMS}$	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
$V_{SC}$	S-correction voltage	Spannung bei Anwendung "S-correction"
$V_{sn}$	Snubber capacitor voltage	Spannung bei Anwendung
		"Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß



# **Important** notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an EPCOS product with the properties described in the product specification is suitable for use in a particular customer application.
- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or lifesaving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
- 4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet (www.epcos.com/material). Should you have any more detailed questions, please contact our sales offices.
- 5. We constantly strive to improve our products. Consequently, the products described in this publication may change from time to time. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also reserve the right to discontinue production and delivery of products. Consequently, we cannot guarantee that all products named in this publication will always be available. The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.
- Unless otherwise agreed in individual contracts, all orders are subject to the current version of the "General Terms of Delivery for Products and Services in the Electrical Industry" published by the German Electrical and Electronics Industry Association (ZVEI).



## Important notes

7. The trade names EPCOS, Alu-X, CeraDiode, CeraLink, CeraPad, CeraPlas, CSMP, CSSP, CTVS, DeltaCap, DigiSiMic, DSSP, ExoCore, FilterCap, FormFit, LeaXield, MiniBlue, MiniCell, MKD, MKK, MotorCap, PCC, PhaseCap, PhaseCube, PhaseMod, PhiCap, PQSine, SIFERRIT, SIFI, SIKOREL, SilverCap, SIMDAD, SiMic, SIMID, SineFormer, SIOV, SIP5D, SIP5K, TFAP, ThermoFuse, WindCap are trademarks registered or pending in Europe and in other countries. Further information will be found on the Internet at www.epcos.com/trademarks.